| L Number | Hits | Search Text | DB | Time stamp |
|----------|---------|-----------------------------------------------------------------------------------------|---------------------|--------------------|
| 1 | 54 | (adhesive near (vacuum or air or bubble\$2 or | USPAT; | 2003/02/24 08:12 |
| | | space\$2)) and (chip or die or device) and | US-PGPUB; | |
| ļ | | (semiconductor and ic) | EPO; JPO; | } |
| } | | , | DERWENT; | |
| ĺ | | | IBM_TDB | } |
| 2 | 22 | ((adhesive near (vacuum or air or bubble\$2 | USPAT; | 2003/02/24 08:26 |
| } { | | or space\$2)) and (chip or die or device) and | US-PGPUB; | |
| | | (semiconductor and ic)) and (@ad<19960509) | EPO; JPO; | |
| } | | | DERWENT; | |
| } | | | IBM_TDB | |
| 4 | 3011481 | "13" and (@ad<19960509) | USPAT; | 2003/02/24 08:14 |
| } | | | US-PGPUB; | ĺ |
| { | | | EPO; JPO; | |
| 1 | | | DERWENT; | |
| | 5.0 | (- dlo - siere - see - (- see - see - see - see - see | IBM_TDB | 2002/02/24 02 04 |
| 3 | 56 | (adhesive near (porous or pore or air or bubble\$2 or space\$2 or opening)) and (chip | USPAT; US-PGPUB; | 2003/02/24 08:24 |
| 1 | | or die or device) and (semiconductor and ic) | EPO; JPO; | |
| 1 | | or are or device, and (semiconductor and ic) | DERWENT; | |
| } | | | IBM TDB | j |
| 5 | 879 | (adhesive with (porous or pore or air or | USPAT; | 2003/02/24 09:00 |
| | 0.5 | bubble\$2 or space\$2 or opening or thread | US-PGPUB; | 2000, 02, 21 01100 |
| } | | pregnate)) and (chip or die or device) and | EPO; JPO; | |
| } | | (semiconductor and ic) | DERWENT; | } |
| } | | | IBM TDB | { |
| 6 | 300 | ((adhesive with (porous or pore or air or | USPAT; | 2003/02/24 09:04 |
| ł | | bubble\$2 or space\$2 or opening or thread | US-PGPUB; | |
| (| | pregnate)) and (chip or die or device) and | EPO; JPO; | |
| | | (semiconductor and ic)) and (@ad<19960509) | DERWENT; | |
| _ | | (,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,, | IBM_TDB | |
| 7 | 5 | ("4760440" "4866506" "4910581" | USPAT | 2003/02/24 08:32 |
| 9 | 14732 | "4942452" "5296738").PN. | TIODAM. | 2002/02/24 00 03 |
| 9 | 14/32 | ((adhesive or bond) with ((porous or pore or air or bubble\$2 or space\$2 or opening or | USPAT; US-PGPUB; | 2003/02/24 09:03 |
| } | | thread\$2 or pregnate\$2)) and (stress or | EPO; JPO; | |
| \ | | relax or vent)) | DERWENT; | |
| } | | LOZGIN OZ VOILO, , | IBM TDB | |
| 10 | 3367 | (adhesive or bond) with ((porous or pore or | USPAT; | 2003/02/24 09:04 |
| | | air or bubble\$2 or space\$2 or opening or | US-PGPUB; | ,, |
| } | | thread\$2 or pregnate\$2) and (stress or relax | EPO; JPO; | |
| | | or vent)) | DERWENT; | 1 |
|]. | | | IBM_TDB | |
| 11 | 1940 | ((adhesive or bond) with ((porous or pore or | USPAT; | 2003/02/24 09:04 |
| 1 | | air or bubble\$2 or space\$2 or opening or | US-PGPUB; | |
| } | | thread\$2 or pregnate\$2) and (stress or relax | EPO; JPO; | |
| { | | or vent))) and (@ad<19960509) | DERWENT; | |
| 10 | | | IBM_TDB | 2222/22/24 25 25 |
| 12 | 544 | (((adhesive or bond) with ((porous or pore | USPAT; | 2003/02/24 09:05 |
| 1 | | or air or bubble\$2 or space\$2 or opening or | US-PGPUB; | |
| Í | | thread\$2 or pregnate\$2) and (stress or relax | EPO; JPO; | |
| } | | or vent))) and (@ad<19960509)) and (chip or die or semiconductor) | DERWENT; IBM TDB | |
| | | die of Bemiconduccof/ | TDM_TDR | |